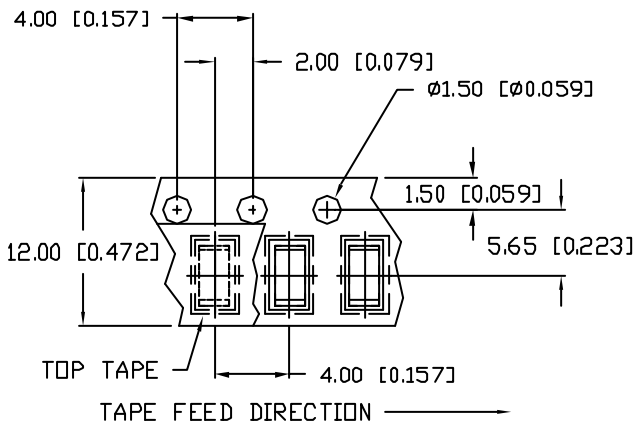
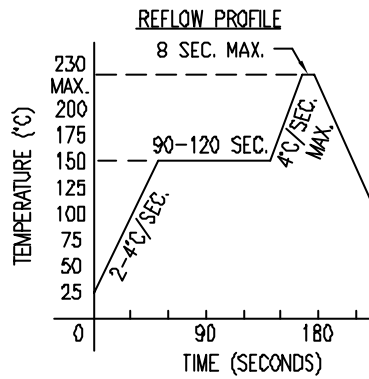
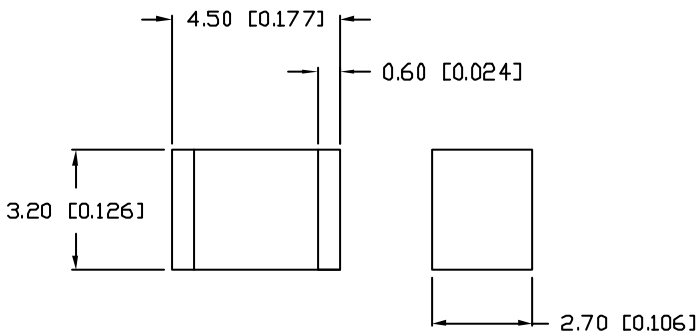


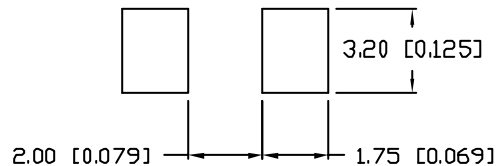
UNCONTROLLED DOCUMENT

GT-SMD1

REV.	E.C.N. NUMBER
A	E.C.N. #11148.



RECOMMENDED SOLDER PAD LAYOUT



PARAMETER	ENVIRONMENTAL S
D.C. FIRING VOLTAGE:	
IMPULSE CURRENT:	
A.C. DISCHARGE CURRENT:	
INSULATION RESISTANCE:	
INTER-ELECTRODE CAPACITANCE:	

TEST	METH
VIBRATION TESTING:	204
SHOCK	213
HUMIDITY:	103
TEMPERATURE CYCLING:	102
BAROMETRIC PRESSURE:	105
THERMAL SHOCK:	107
SOLDERABILITY:	201

NOTES:

1. 500 PIECES

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.038), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.05

UNCONT

REV. A	PART NUMBER GT-SMD181240022-TR	<p><b>CONFIDENTIAL INFORMATION</b></p> <p>THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.</p> <p><b>RELIABILITY NOTE</b></p> <p>OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.</p>	
3.2 x 4.5mm SURFACE MOUNT SURGE, ARRESTOR, 400V.		DRAWN BY: JC	CHECKED: